

N-channel 600 V, 10.4 Ω typ., 0.44 A SuperMESH™ Power MOSFET in a SOT-223 package

Datasheet - production data

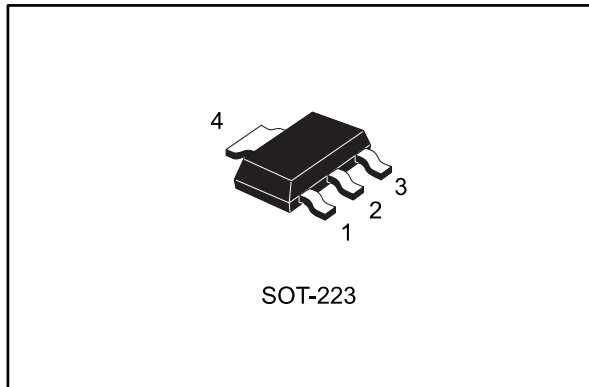
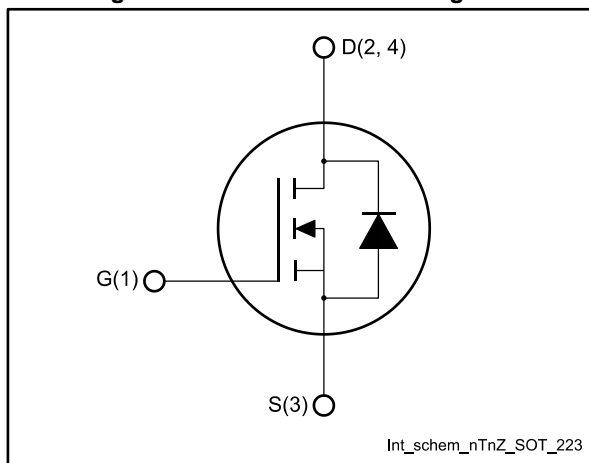


Figure 1: Internal schematic diagram



Features

Order code	V _{DS}	R _{DS(on)} max.	I _D	P _{TOT}
STN1NK60ZL	600 V	15 Ω	0.44 A	3.3 W

- 100% avalanche tested
- Extremely high dv/dt capability
- Gate charge minimized
- ESD improved capability

Applications

- Switching applications

Description

This high voltage device is an N-channel Power MOSFET developed using the SuperMESH™ technology by STMicroelectronics, an optimization of the well-established PowerMESH™. In addition to a significant reduction in on-resistance, this device is designed to ensure a high level of dv/dt capability for the most demanding applications.

Table 1: Device summary

Order code	Marking	Package	Packing
STN1NK60ZL	1NK60ZL	SOT-223	Tube

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1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage	600	V
V_{GS}	Gate-source voltage	± 20	V
I_D	Drain current (continuous) at $T_{amb} = 25\text{ }^\circ\text{C}$	0.44	A
I_D	Drain current (continuous) at $T_{amb} = 100\text{ }^\circ\text{C}$	0.3	A
$I_{DM}^{(1)}$	Drain current (pulsed)	1.8	A
P_{TOT}	Total dissipation at $T_{amb} = 25\text{ }^\circ\text{C}$	3.3	W
$dv/dt^{(2)}$	Peak diode recovery voltage slope	3	V/ns
T_j	Operating junction temperature range	- 55 to 150	$^\circ\text{C}$
T_{stg}	Storage temperature range		

Notes:

(1) Pulse width limited by safe operating area.

(2) $I_{SD} \leq 0.3\text{ A}$, $di/dt \leq 200\text{ A}/\mu\text{s}$, $V_{DD} = 80\%V_{(BR)DSS}$

Table 3: Thermal data

Symbol	Parameter	Value	Unit
$R_{thj-amb}^{(1)}$	Thermal resistance junction- ambient max	38	$^\circ\text{C}/\text{W}$

Notes:

(1) When mounted on 1 inch² FR-4 board, 2 Oz Cu, $t < 3\text{ s}$

Table 4: Avalanche characteristics

Symbol	Parameter	Value	Unit
I_{AR}	Avalanche current, repetitive or not repetitive (pulse width limited by T_{jmax})	0.3	A
E_{AS}	Single pulse avalanche energy (starting $T_j = 25\text{ }^\circ\text{C}$, $I_D = I_{AR}$, $V_{DD} = 50\text{ V}$)	150	mJ

2 Electrical characteristics

$T_C = 25\text{ °C}$ unless otherwise specified

Table 5: On/off-state

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0\text{ V}$, $I_D = 1\text{ mA}$	600			V
I_{DSS}	Zero gate voltage drain current	$V_{GS} = 0\text{ V}$, $V_{DS} = 600\text{ V}$			1	μA
		$V_{GS} = 0\text{ V}$, $V_{DS} = 600\text{ V}$ $T_C = 125\text{ °C}^{(1)}$			50	μA
I_{GSS}	Gate body leakage current	$V_{DS} = 0\text{ V}$, $V_{GS} = \pm 20\text{ V}$			± 100	nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}$, $I_D = 50\text{ }\mu\text{A}$	0.9	1.7	2	V
$R_{DS(on)}$	Static drain-source on-resistance	$V_{GS} = 10\text{ V}$, $I_D = 0.25\text{ A}$		10.4	15	Ω

Notes:

⁽¹⁾Defined by design, not subject to production test.

Table 6: Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	$V_{GS} = 0\text{ V}$, $V_{DS} = 25\text{ V}$, $f = 1\text{ MHz}$	-	125	-	pF
C_{oss}	Output capacitance		-	13	-	pF
C_{riss}	Reverse transfer capacitance		-	2	-	pF
Q_g	Total gate charge	$V_{DD} = 480\text{ V}$, $I_D = 0.8\text{ A}$	-	9.4	-	nC
Q_{gs}	Gate-source charge	$V_{GS} = 10\text{ V}$	-	0.8	-	nC
Q_{gd}	Gate-drain charge	(see Figure 15: "Test circuit for gate charge behavior")	-	4.5	-	nC

Table 7: Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 300\text{ V}$, $I_D = 0.4\text{ A}$, $R_G = 4.7\text{ }\Omega$ $V_{GS} = 10\text{ V}$ (see Figure 14: "Test circuit for resistive load switching times" and Figure 19: "Switching time waveform")	-	4.4	-	ns
t_r	Rise time		-	4	-	ns
$t_{d(off)}$	Turn-off delay time		-	18.4	-	ns
t_f	Fall time		-	41	-	ns

Table 8: Source-drain diode

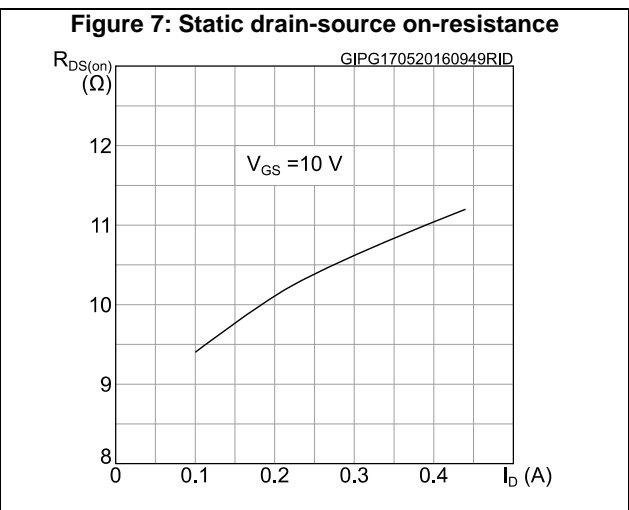
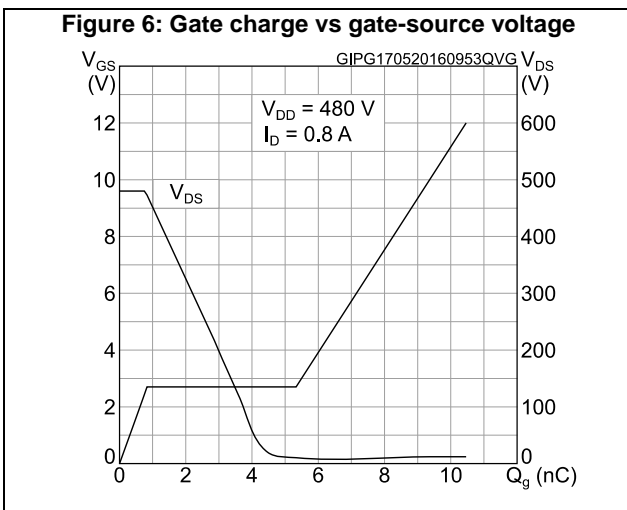
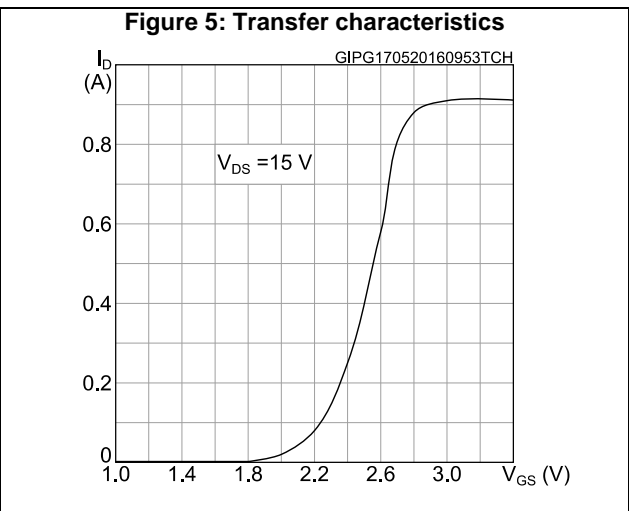
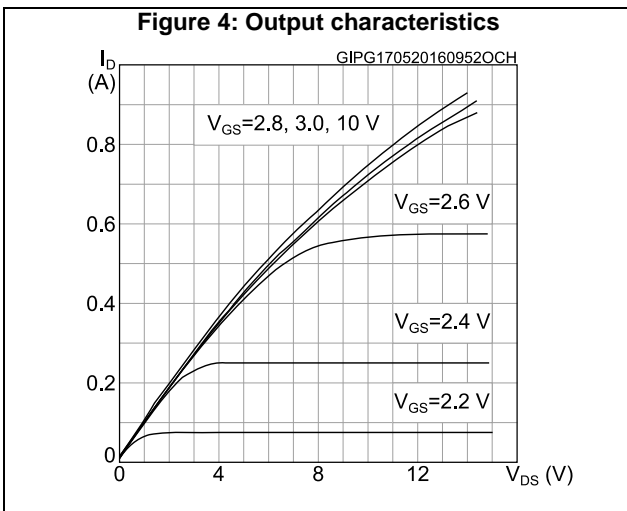
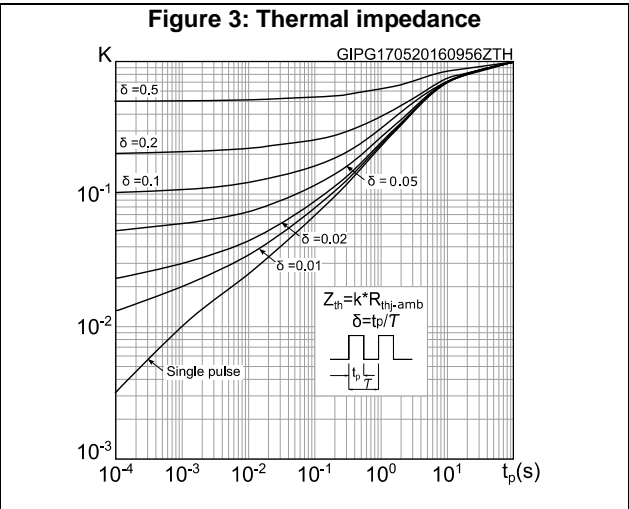
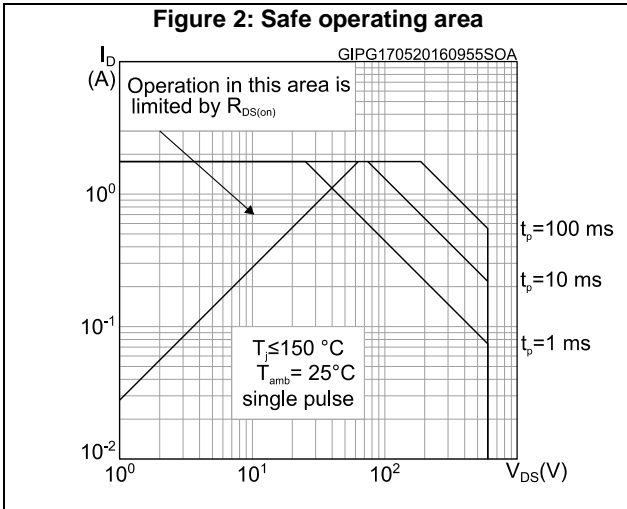
Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-		0.44	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		1.8	A
$V_{SD}^{(2)}$	Forward on voltage	$V_{GS} = 0\text{ V}$, $I_{SD} = 0.44\text{ A}$	-		1.5	V
t_{rr}	Reverse recovery time	$I_{SD} = 0.8\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$, $V_{DD} = 60\text{ V}$ (see Figure 16: "Test circuit for inductive load switching and diode recovery times")	-	155		ns
Q_{rr}	Reverse recovery charge		-	232		nC
I_{RRM}	Reverse recovery current		-	3		A
t_{rr}	Reverse recovery time	$I_{SD} = 0.8\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$ $V_{DD} = 60\text{ V}$, $T_j = 150\text{ °C}$ (see Figure 16: "Test circuit for inductive load switching and diode recovery times")	-	186		ns
Q_{rr}	Reverse recovery charge		-	297		nC
I_{RRM}	Reverse recovery current		-	3.2		A

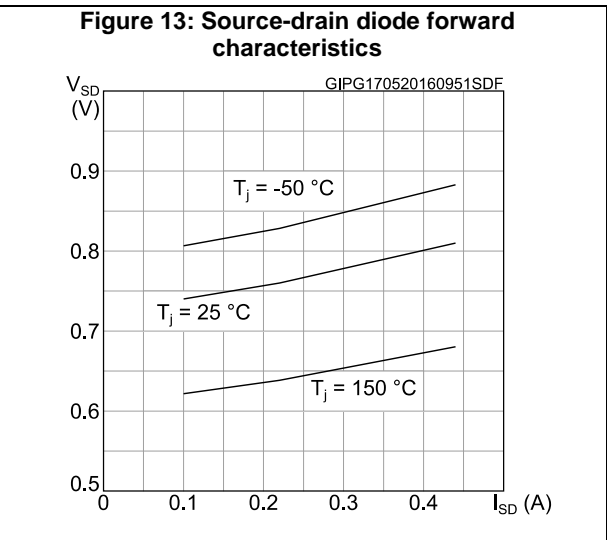
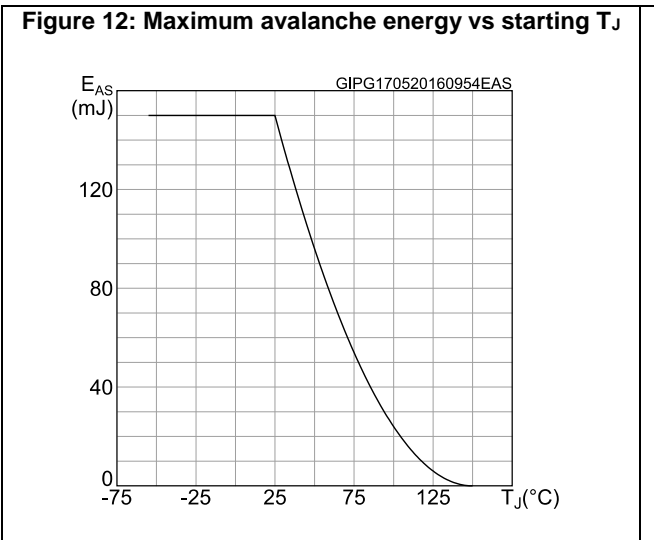
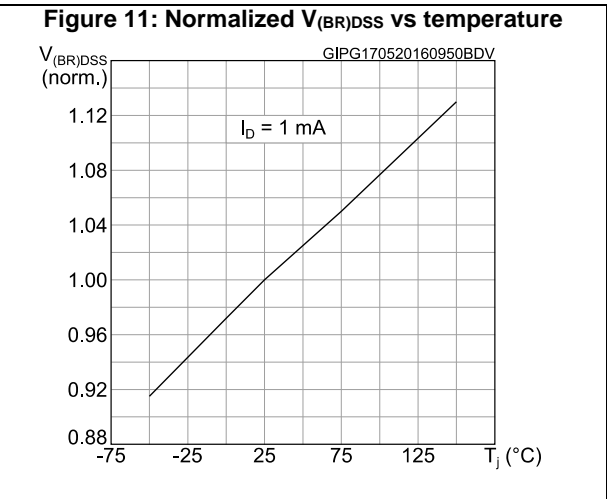
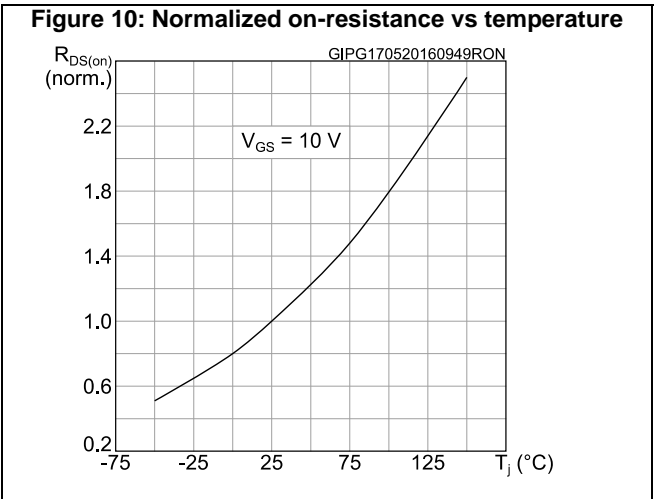
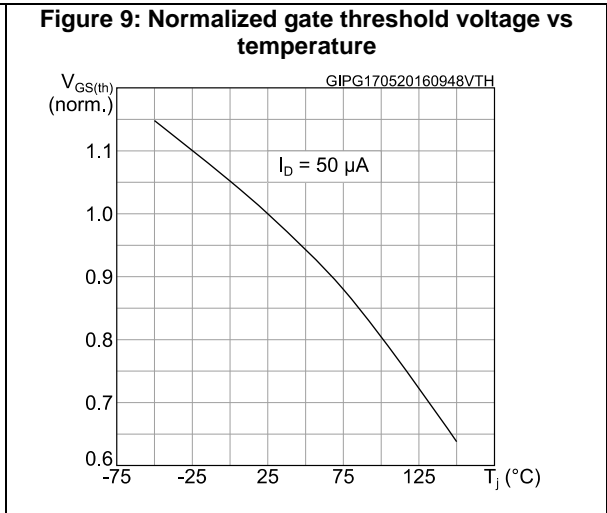
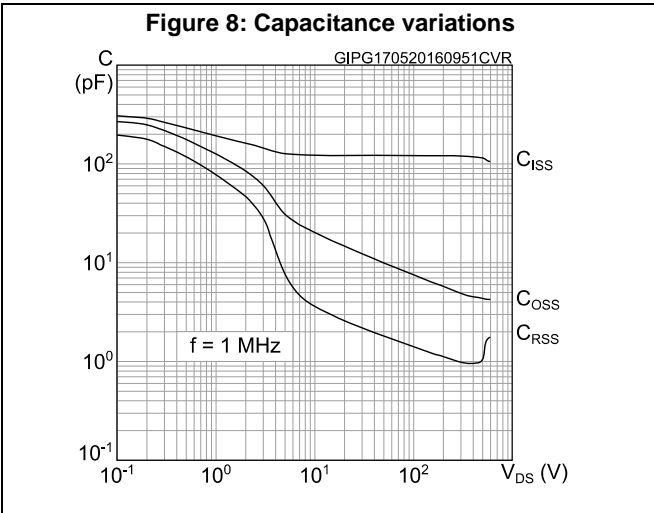
Notes:

(1)Pulse width limited by safe operating area

(2)Pulsed: pulse duration = 300 μs , duty cycle 1.5%

2.2 Electrical characteristics (curves)





3 Test circuits

Figure 14: Test circuit for resistive load switching times



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Figure 15: Test circuit for gate charge behavior



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Figure 16: Test circuit for inductive load switching and diode recovery times



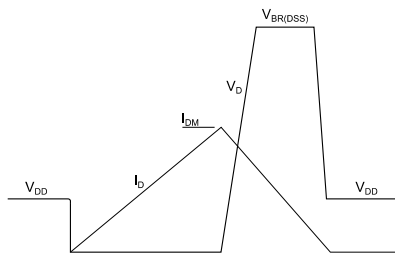
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Figure 17: Unclamped inductive load test circuit



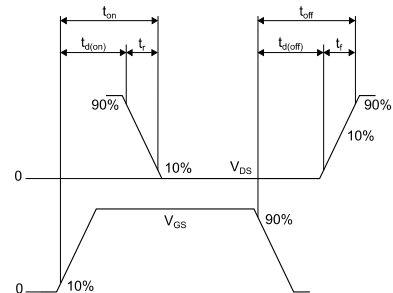
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Figure 18: Unclamped inductive waveform



AM01472v1

Figure 19: Switching time waveform



AM01473v1

4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

4.1 SOT-223 package information

Figure 20: SOT-223 package outline

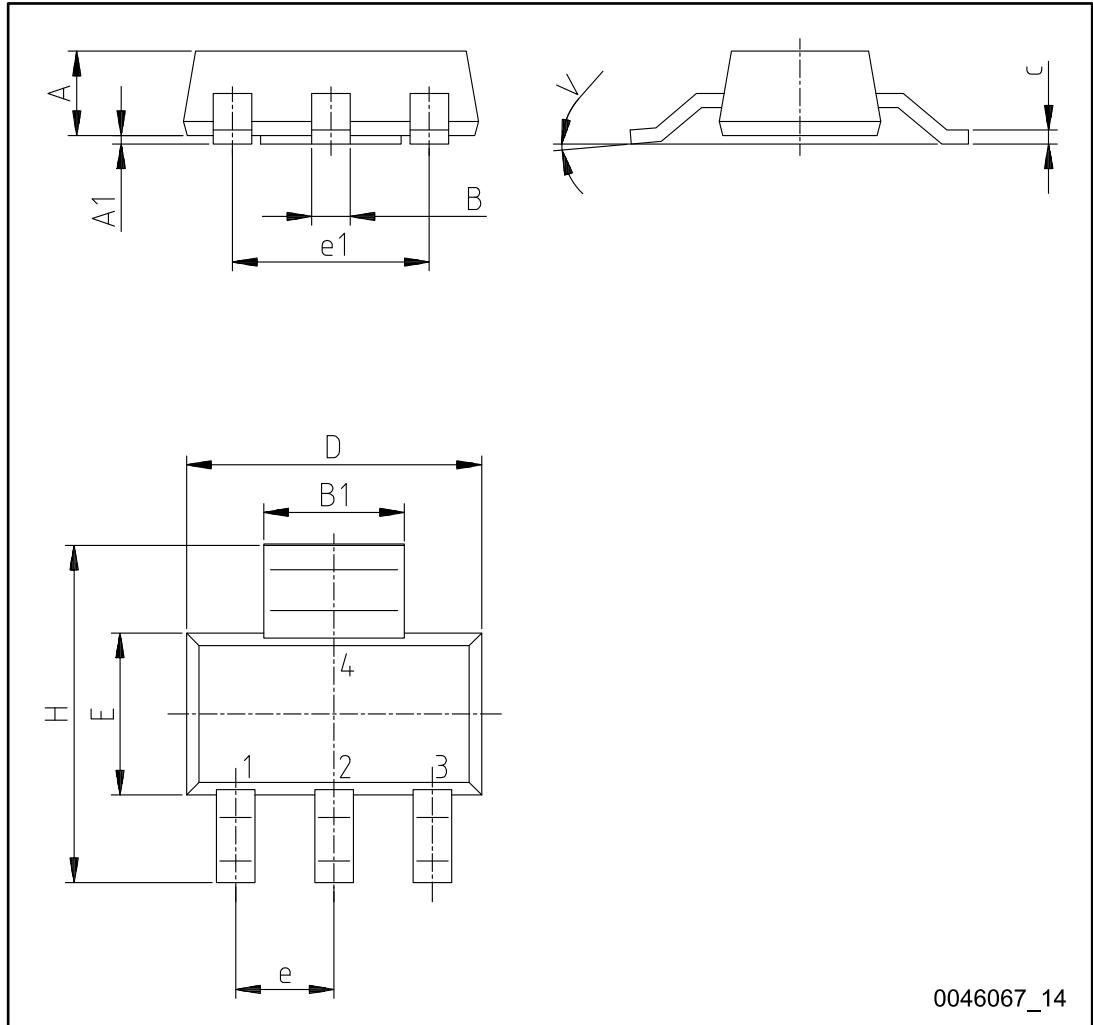
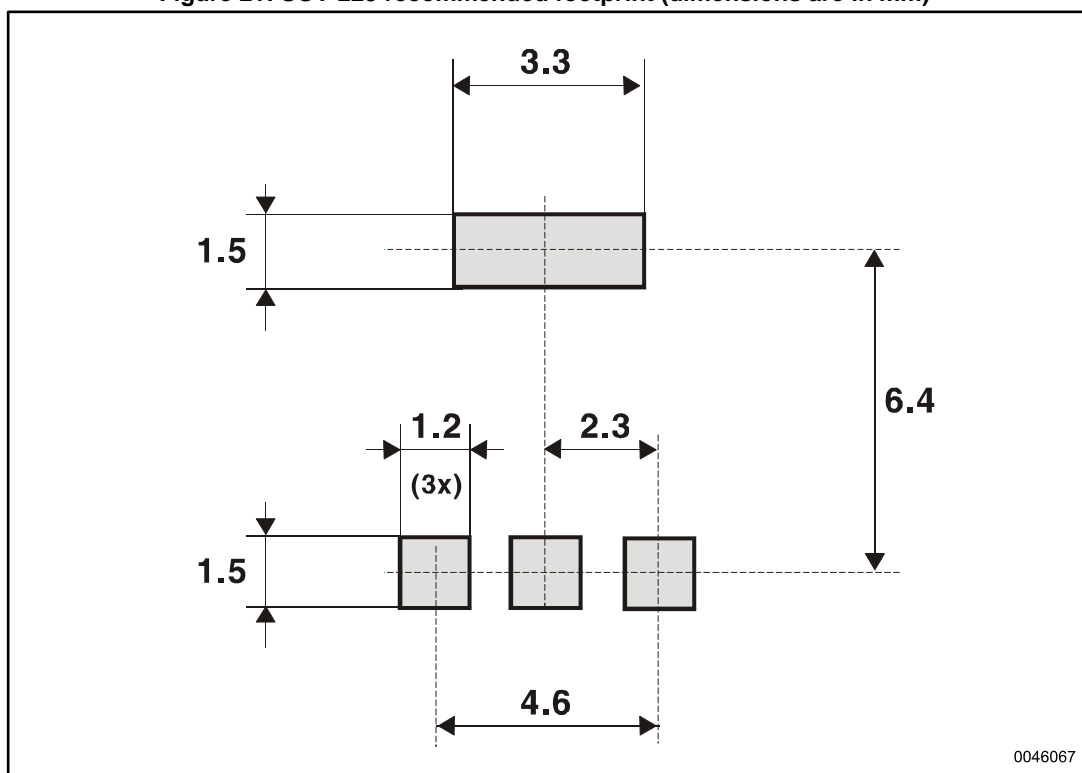


Table 9: SOT-223 package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A			1.8
A1	0.02		0.1
B	0.6	0.7	0.85
B1	2.9	3	3.15
c	0.24	0.26	0.35
D	6.3	6.5	6.7
e		2.3	
e1		4.6	
E	3.3	3.5	3.7
H	6.7	7.0	7.3
V			10°

Figure 21: SOT-223 recommended footprint (dimensions are in mm)



0046067

5 Revision history

Table 10: Document revision history

Date	Revision	Changes
12-Nov-2015	1	First release.
05-Dec-2016	2	Modified: features in cover page Modified Table 2: "Absolute maximum ratings" , Table 3: "Thermal data" , Table 4: "Avalanche characteristics" , Table 5: "On/off-state" , Table 6: "Dynamic" , Table 7: "Switching times" and Table 8: "Source-drain diode" Datasheet promoted from preliminary data to production data Modified Section 3.1: "Electrical characteristics (curves)" Minor text changes

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